



VMDSEMI

**VTTL060R50BNA**

**Datasheet**



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## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
600V	5.0Ω@10V	2A

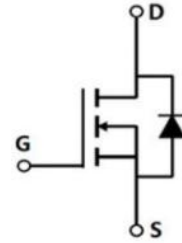


Figure 1 Symbol of VTTL060R50BNA

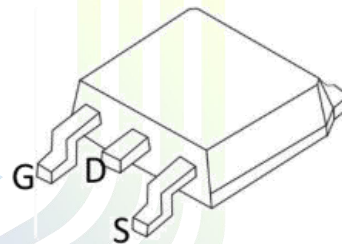
## Features

- Low  $R_{DS(on)}$
- Low FOM
- Extremely low switching loss
- Good stability and uniformity

## Application

- Consumer electronics power supply
- LED Lighting
- Standby Power
- Charger

## Package Type



**TO-252-2L**

Figure 2 Package Type of VTTL060R50BNA

## Ordering Information

Product Name	Package
VTTL060R50BNA	TO-252-2L

**5.0Ω, 600V, N-Channel Power MOSFET**
**VTTL060R50BNA**
**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	600	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	2	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	9	
Avalanche Current <sup>Note3</sup>	$I_{AS}$	5.9	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	8.7	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	56.8	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case <sup>Note6</sup>	$R_{\theta JC}$		2.1		°C/W



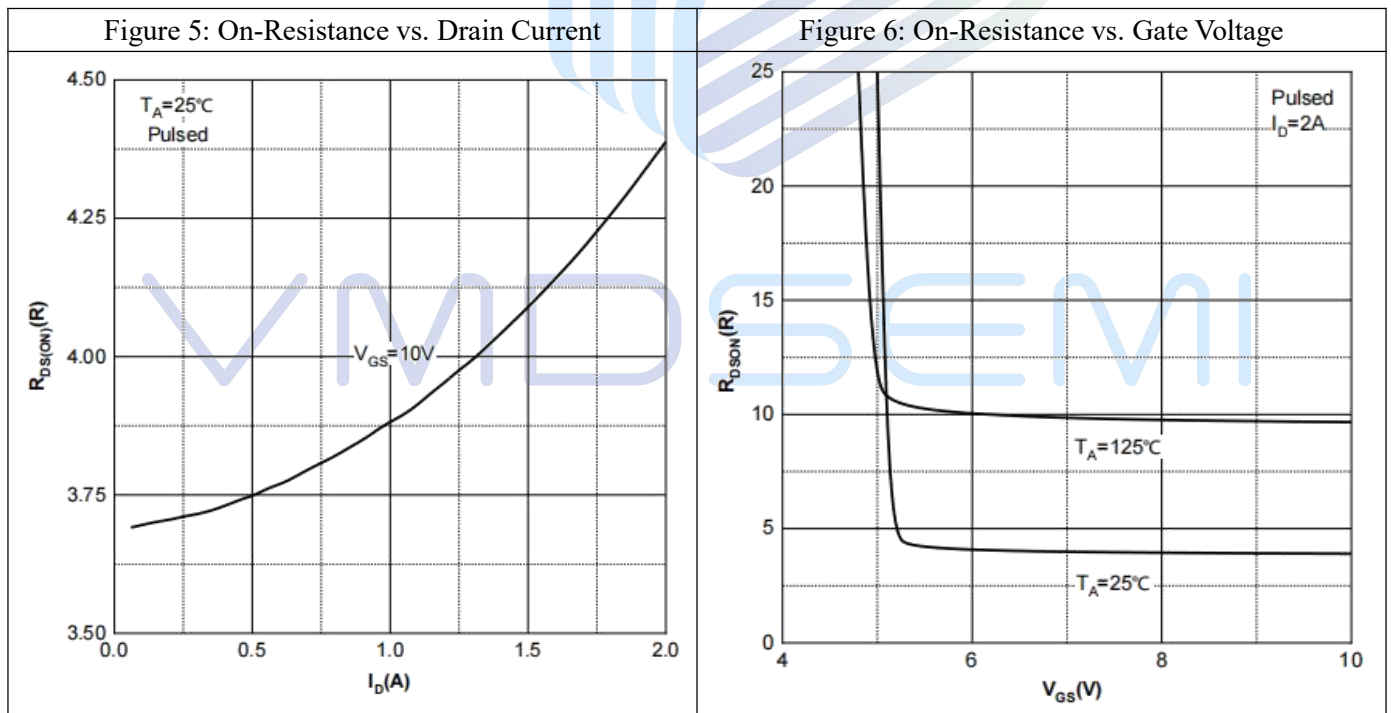
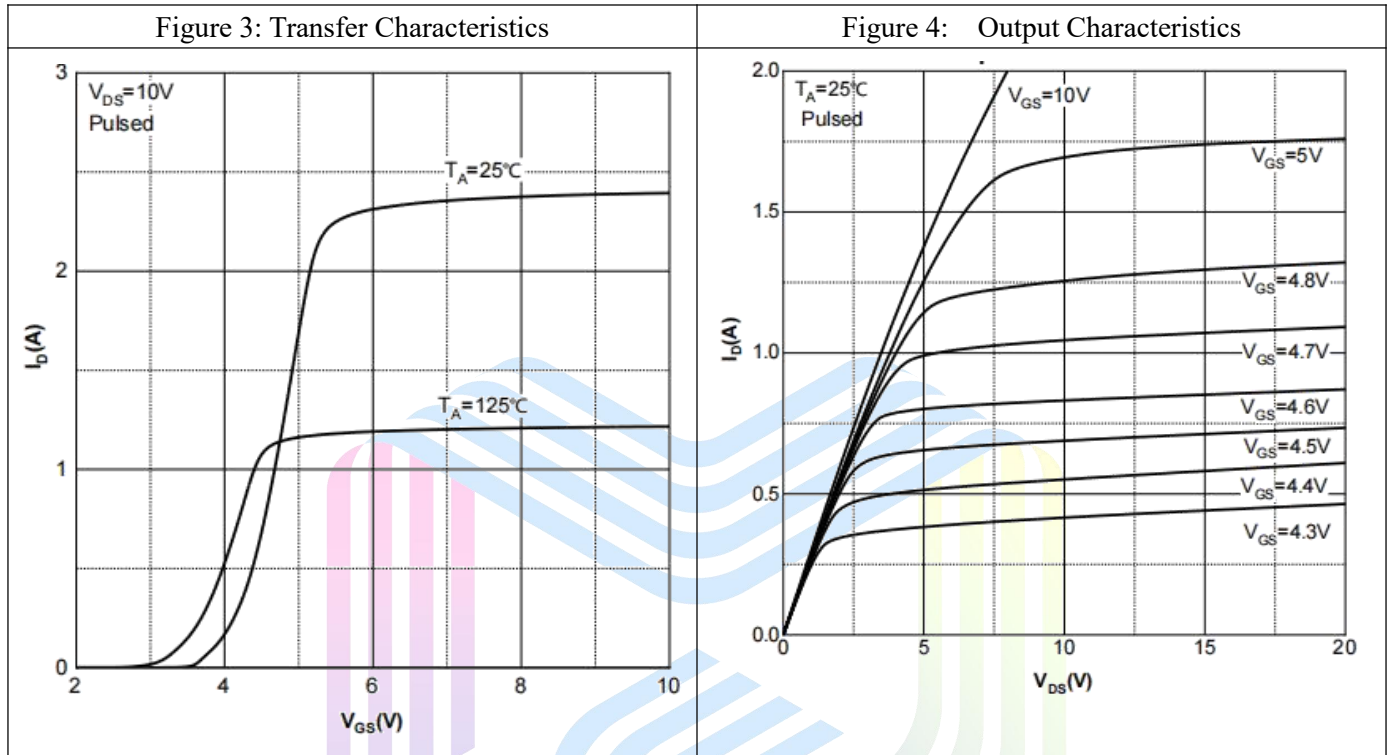
**5.0Ω, 600V, N-Channel Power MOSFET**
**VTTL060R50BNA**
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

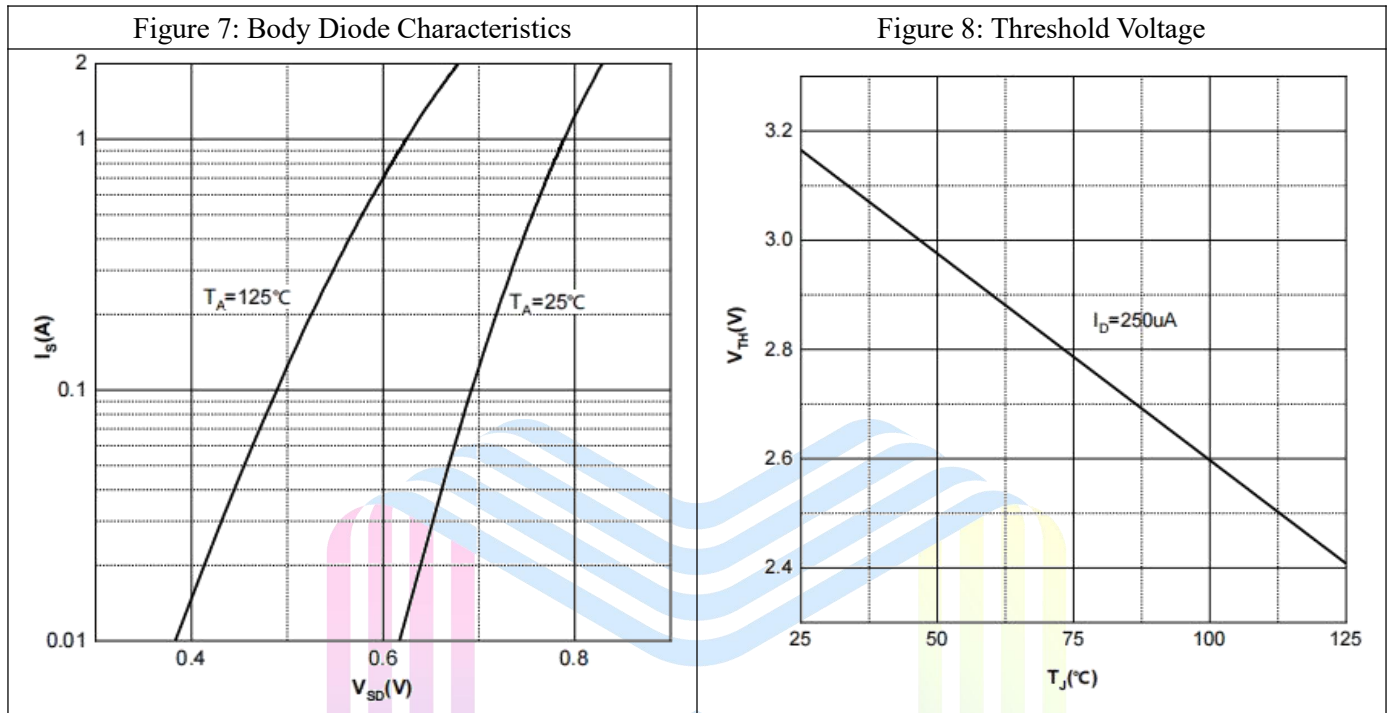
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=600V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	3.2	4.0	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1A$		3.9	5.0	$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V$		339		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		25.3		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		2.2		pF
Total Gate Charge	$Q_g$	$V_{DS}=300V$		3.2		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		1.2		
Gate-Drain Charge	$Q_{gd}$	$I_D=1A$		1.4		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		3.3		$\Omega$
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=300V$		12		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		21		
Turn-off Delay Time	$t_{d(off)}$	$I_D=2A$		30		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		24		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=2A$			1.2	V

Notes :

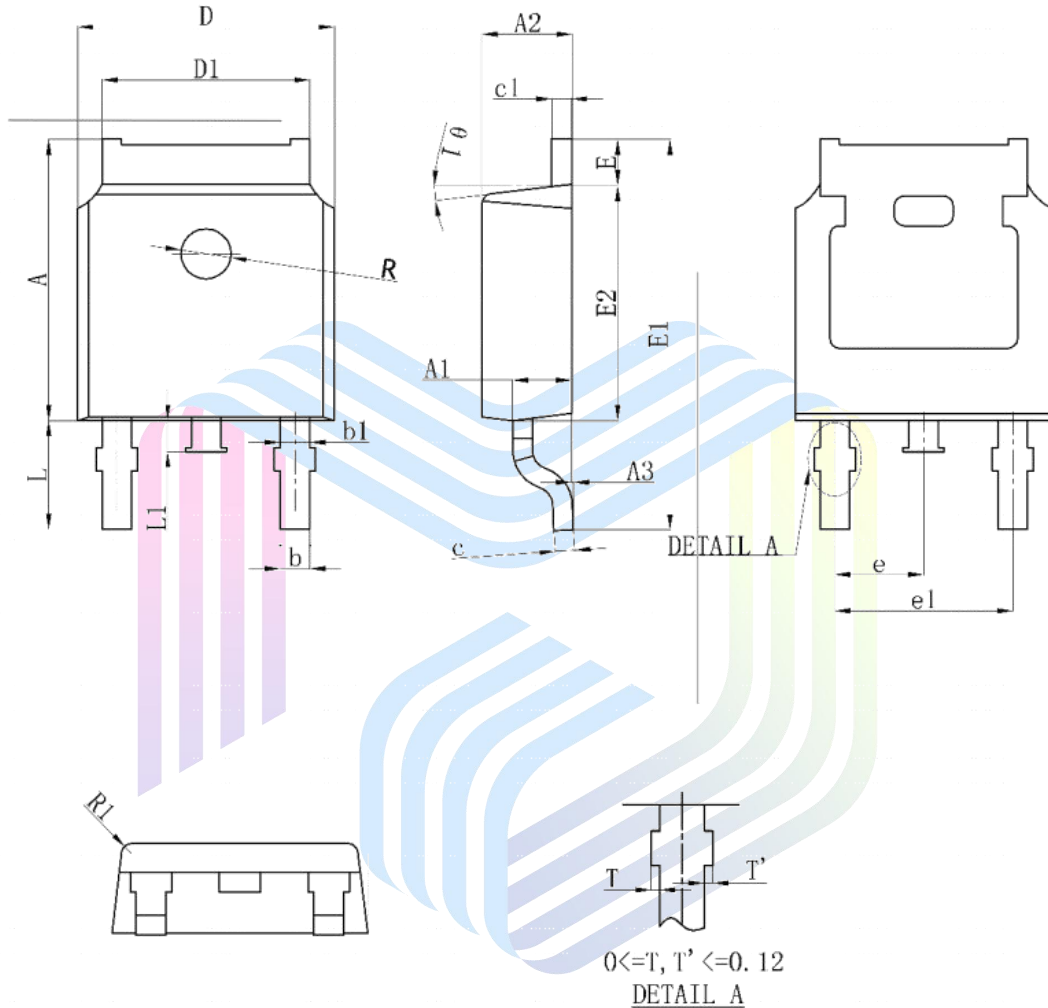
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
3. $E_{AS}$  condition:  $V_{DD} = 100V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- 4.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 5.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 6.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

### Typical Performance Characteristics





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**Mechanical Dimensions:**
**TO-252-2L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.050	7.150	0.278	0.281
A1	0.960	1.060	0.038	0.042
A2	2.200	2.400	0.087	0.094
A3	0.000	0.100	0.000	0.004
b	0.760REF		0.030REF	
b1	1.000REF		0.039REF	
c	0.508REF		0.020REF	
c1	0.508REF		0.020REF	
D	6.550	6.650	0.258	0.262
D1	5.100	5.460	0.201	0.215
E	0.950	1.050	0.037	0.041
E1	9.700	10.400	0.382	0.409
E2	6.000	6.200	0.236	0.244
e	2.286BSC		0.090BSC	
e1	4.572REF		0.180REF	
L	2.650	2.950	0.104	0.116
L1	0.700	0.900	0.028	0.035
θ1	7°REF		7°REF	
R	1.300REF		0.051REF	
R1	0.250REF		0.010REF	

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**Via-Media Semiconductor Limited Company**

<http://www.vmdsemi.com>

**Main Sites:**

**- Headquarters**

Hangzhou Via-Media Semiconductor Co., LTD.  
1305-1306, Building 71, No. 90, Wensan Road, Xihu  
District, Hangzhou, Zhejiang Province, P.R. China  
Tel: +86-0571-8515 0563

**- Chengdu Office**

Chengdu Winhi Semiconductor Co., LTD.  
Floor 15, Building 5, No. 171, Hele 2<sup>nd</sup> Street,  
Chengdu, Sichuan Province, P.R. China  
Tel: +86-028-8505 0771

**- Shanghai**

Shanghai R&D Center.  
1506~1508, Xinyin Building, 888 Yishan Road,  
Shanghai, P.R of China  
Tel: +86- 021-54201999

**- Shenzhen**

Shenzhen Sales Center.  
17B, No.1 Phoenix Building, 2008 Shennan Road,  
Shenzhen, P.R of China  
Tel: +86-0755- 82570682

**- Xi'an**

Xi'an R&D Center  
1703B, Building A, Greenland Center, Jinye Road,  
High-Tech Zone, Xi'an, Shaanxi, P.R of China